

PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| | |
| Name | Execution Date |
| HIDEHIKO OKU | 08/07/2018 |
| ICHIRO HIDE | 08/08/2018 |
| RECEIVING PARTY DATA | |
| Name: | AIR WATER INC. |
| Street Address: | 2, KITA 3-JO, NISHI 1-CHOME, CHUO-KU |
| City: | SAPPORO-SHI, HOKKAIDO |
| State/Country: | JAPAN |
| Postal Code: | 0600003 |
| PROPERTY NUMBERS Total: 1 | |
| | |
| Property Type | Number |
| Application Number: | 17580299 |
| CORRESPONDENCE DATA | |
| Fax Number: | (312)876-2020 |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | |
| Phone: | 312-876-1800 |
| Email: | lbowen@woodphillips.com |
| Correspondent Name: | WOOD, PHILLIPS, KATZ, CLARK & MORTIMER |
| Address Line 1: | 500 W. MADISON STREET |
| Address Line 2: | SUITE 1130 |
| Address Line 4: | CHICAGO, ILLINOIS 60661-2562 |
| ATTORNEY DOCKET NUMBER: | TSU11102P00041US |
| NAME OF SUBMITTER: | JOHN S. MORTIMER |
| SIGNATURE: | /John S. Mortimer/ |
| DATE SIGNED: | 01/10/2023 |
| Total Attachments: 4 | |
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| source=17580299_Assignment#page4.tif | |

Assignment

Serial No.: 15/999,243

Filed: August 17, 2018

In Consideration of One Dollar and other good and valuable considerations, the receipt of which is hereby acknowledged, the entire right, title and interest in the invention or improvements of the undersigned in A compound semiconductor substrate, a pellicle film, and a method for manufacturing a compound semiconductor substrate and in the application for Letters Patent of the United States therefor, executed by the undersigned, and in any reissue or extension of any Letters Patent that may be granted upon said application are hereby assigned by the undersigned to AIR WATER INC., an JAPAN corporation, having offices at 2, Kita 3-jo Nishi 1-chome Chuo-ku, Sapporo-shi, Hokkaido 0500003 JAPAN, and the successors, legal representatives and assigns of AIR WATER INC. (hereinafter collectively called said Assignee), and the Commissioner for Patents is hereby authorized and requested by the undersigned to issue said Letters Patent to said Assignee.

For said considerations it is hereby agreed by the undersigned, upon the request of said Assignee, to execute any necessary and proper oaths or affidavits relating to said application or required for the filing or prosecution of any divisional or continuing application thereof or for the filing or prosecution of any application for the reissue or extension of any Letters Patent that may be granted on said invention or improvements that said Assignee may deem necessary or expedient, and for the said considerations it is further agreed by the undersigned, upon the request of said Assignee, in the event of said application or any division thereof, or Letters Patent issued thereon, or any reissue or application for the reissue thereof, becoming involved in interference, to cooperate to the best of the ability of the undersigned with said Assignee in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, and further to perform, upon such request, any and all affirmative acts to obtain said Letters Patent and vest all rights therein hereby conveyed in the said Assignee as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made. And for the said considerations the entire right, title and interest in said invention or improvements, including all priority rights, and the right to claim priority rights and the privileges and benefits thereof, including those under the International Convention, and all other Conventions, and the right to file applications for patent in said Assignee's own name for said invention or improvements in each and every country of the world are hereby assigned and granted by the undersigned to said Assignee. It is further agreed by the undersigned, upon the request of said Assignee, to execute any and all documents that shall be required of the undersigned to be executed in connection with any and all applications for foreign Letters Patent therefor, including the prosecution thereof, and to execute any and all documents necessary to invest title in said foreign applications and patents in said Assignee. The undersigned also further agrees, for the said considerations, upon the request of said Assignee, to promptly perform all lawful acts deemed by said Assignee to be necessary or advisable in connection with maintaining, enforcing, or transferring the resulting grants of said Letters Patent in the United States or foreign countries. It is agreed that such lawful acts include, but are not limited to, taking oaths, executing declarations, powers, assignments and other papers and giving testimony.

Our Docket Number

Serial No.: 15/999,243

Filed: August 17, 2018

The attorneys of record in such application for patent are hereby authorized and requested by the undersigned to insert in this Assignment the date and serial number thereof in the places provided therefor.

Hidehiko Oku
OKU, Hidehiko

of August Executed this 17th day, 2018.

State of _____)
County of _____) ss.

On _____, 2017, OKU, Hidehiko appeared before me, a Notary Public, in and for the State and County aforesaid, and acknowledged that he freely and voluntarily subscribed and executed the foregoing Assignment for the purposes and uses therein expressed.

(SEAL)

Notary Public

My Commission Expires: _____

Assignment

Serial No.: 15/999,243

Filed: August 17, 2018

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